TIGER CLAW™ SOCKET STRIP

(2.00 mm) .0787" PITCH • MMS SERIES

MMS

Board Mates:
TMMH, TMM, MTMM, MMT, TW, LTMM, ZLTMM, TSH

Cable Mates:
TCMD

SPECIFICATIONS

Insulator Material:
Black LCP

Contact Material:
Phosphor Bronze

Plating:
Sn or Au over 50 µ" (1.27 µm) Ni

Current Rating (MMS/TMM):
3.9 A per pin (2 pins powered)

Operating Temp Range:
-55 °C to +125 °C with Gold
-55 °C to +105 °C with Tin

Insertion Depth:
DH = (2.13 mm) .084" to (2.79 mm) .110"
SH = (2.13 mm) .084" minimum or pass-through
Top Entry DV/SV = (2.13 mm) .084" to
(4.32 mm) .170" Bottom Entry DV/SV =
(4.27 mm) .168" minimum (Plus board)

PROCESSING

Lead-Free Solderable:
Yes

SMT Lead Coplanarity:
(0.15 mm) .006" max*
(0.040" stencil solution may be available; contact IPG@samtec.com)

Note:
Some lengths, styles and options are non-standard, non-returnable.

ALSO AVAILABLE

MOQ Required:
Alignment Pin (~DV only)
Locking clips and Through-hole pass-through options
Other platings

OTHER OPTION

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